

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC6209xxxxDR-G  
Typical Mass:           6       mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.641	Silicon	106800	7440-21-3
	-	Arsenic	5	7440-38-2
Lead pad	1.100	Nickel	183400	7440-02-0
	0.087	Silver	14600	7440-22-4
	0.016	Gold	2700	7440-57-5
Die attach	0.016	Epoxy Resin	2700	—
	0.012	Silica	2100	60676-86-0
Bonding wire	0.040	Gold	6700	7440-57-5
Resin	3.678	Silica	613000	60676-86-0
	0.225	Epoxy Resin	37500	—
	0.184	Phenol Resin	30600	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."